



# PRODUCT/PROCESS CHANGE NOTIFICATION

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PCN HPC-AUD/06/2010  
Notification Date 09/01/2006

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**FROM GOLD TO COPPER WIRE BONDING FOR PDIP.4 PRODUCTS**

**AUD - AUDIO**

**Table 1. Change Identification**

Product Identification (Product Family/Commercial Product)	PDIP16/20 cu.4 Audio Division products
Type of change	Package assembly material change
Reason for change	Bonding wire material change
Description of the change	From gold to copper wire
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Internal sales type change only
Manufacturing Location(s)	1]St Muar - Malaysia

**Table 2. Change Implementation Schedule**

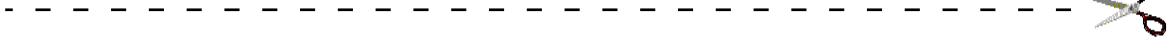
Forecasted implementation date for change	01-Dec-2006
Forecasted availability date of samples for customer	01-Oct-2006
Forecasted date for <b>STMicroelectronics</b> change Qualification Plan results availability	30-Aug-2006
Estimated date of changed product first shipment	01-Dec-2006

**Table 3. Change Responsibility**

	<b>Name</b>	<b>Signature</b>	<b>Date</b>
Division Product Manager	Andrea Onetti		Aug.30 ,06
Division Q.A. Manager	Massimo Piccoli		Aug.30 ,06
Division Marketing Manager	Marco Angelici		Aug.30 ,06

**Table 4. List of Attachments**

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt		<b>PCN HPC-AUD/06/2010</b>
Please sign and return to STMicroelectronics Sales Office		<b>Notification Date 09/01/2006</b>
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved  <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	Name:	
	Title:	
	Company:	
	Date:	
	Signature:	
Remark ..... ..... ..... ..... .....		



## **FROM GOLD TO COPPER BONDING WIRE FOR PDIP.4 PRODUCTS**

Following a Company program of package improvement we are on going to change the bonding wire material from gold to copper on PDIP 16/20 cu.4 products assembled in our Muar plant

The qualification of 2 mils copper wires on PDIP.4 package achieved by extension of SIL package, because of same assy line and wire bonding equipment.  
No additional Reliability test planned since the SIL package already qualified by CMG/TPA in the 2001

The Package Qualification Certificate of PDIP.4 Cu wires (QC-55-06) available upon request.

We will start from December 2006 onward to convert all products to the copper wires. Samples will be available upon request

Please inform your customers about it and feedback their answer.

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